

# MSC49N60X

## 40V N-Channel MOSFETs

### Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

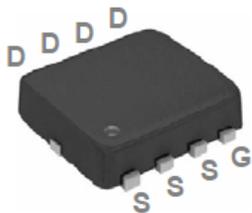
### Features

- 40V,140A,  $R_{DS(ON)} = 2.8m\Omega @ V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- Green Device Available
- RoHS compliant package

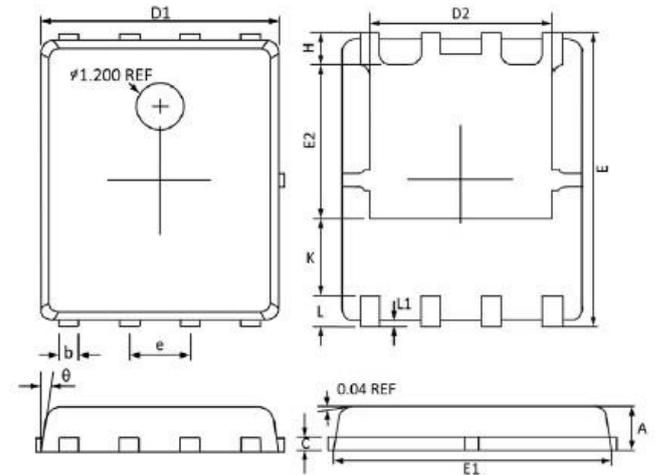
### Applications

- MB / VGA / Vcore
- POL Applications
- SMPS 2nd SR

### PPAK5X6 Pin Configuration

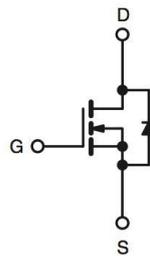


**RoHS  
COMPLIANT**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°

### Graphic symbol



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

### Absolute Maximum Ratings ( $T_A=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DS}$	Drain-Source Voltage	40	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Drain Current - Continuous ( $T_C=25^\circ C$ ) (Chip Limitation)	100	A
	Drain Current - Continuous ( $T_C=100^\circ C$ ) (Chip Limitation)	63	A
$I_{DM}$	Drain Current - Pulsed <sup>1</sup>	400	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	312	mJ

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### Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Value	Unit
I <sub>AS</sub>	Single Pulse Avalanched Current <sup>2</sup>	79	A
P <sub>D</sub>	Power Dissipation ( $T_C=25^\circ\text{C}$ )	135	W
	Power Dissipation - Derate above 25°C	1.08	W/°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to +150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Units
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	--	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction to Case	--	0.92	

### Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

#### Off Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = V_{GS}, I_D = 250\mu\text{A}$	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	BVDSS Temperature Coefficient	Reference to 25°C, $I_D=1\text{mA}$		0.03		V/°C
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			±100	nA
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$ $V_{DS} = 32\text{V}, V_{GS} = 0\text{V}, T_J = 125^\circ\text{C}$			1 10	uA

#### On Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
R <sub>DS(on)</sub>	Drain-Source On-Resistance	$V_{GS} = 10\text{V}, I_D = 25\text{A}$ $V_{GS} = 4.5\text{V}, I_D = 12\text{A}$		2.2 2.6	2.8 3.5	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$		-5		mV/°C
g <sub>fs</sub>	Forward Transconductance	$V_{DS} = 10\text{V}, I_D = 2\text{A}$		45		S

#### Dynamic and switching Characteristics

Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
t <sub>d(on)</sub>	Turn-On Delay Time <sup>3,4</sup>	$I_D = 1\text{A}, R_G = 6\Omega,$ $V_{GS} = 10\text{V}, V_{DD} = 20\text{V}$	--	28	50	ns
t <sub>r</sub>	Rise Time <sup>3,4</sup>		--	3.2	6.5	ns
t <sub>d(off)</sub>	Turn-Off Delay Time <sup>3,4</sup>		--	89	160	ns
t <sub>f</sub>	Fall Time <sup>3,4</sup>		--	14	28	ns

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Dynamic and switching Characteristics						
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$Q_g$	Total Gate Charge <sup>3,4</sup>	$V_{DS} = 20\text{ V}$ , $I_D = 10\text{ A}$ , $V_{GS} = 4.5\text{ V}$	--	44.4	80	nC
$Q_{gs}$	Gate-Source Charge <sup>3,4</sup>		--	9.6	18	nC
$Q_{gd}$	Gate-Drain Charge <sup>3,4</sup>		--	16	30	nC
$C_{ISS}$	Input Capacitance	$V_{DS} = 25\text{ V}$ $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	--	4940	7800	pF
$C_{OSS}$	Output Capacitance		--	425	800	pF
$C_{RSS}$	Reverse Transfer Capacitance		--	170	330	pF
$R_g$	Total Gate Charge	$V_{DS} = 0\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	--	1.4	2.8	$\Omega$

Drain-Source Diode Characteristics and Maximum Ratings						
Symbol	Parameter	Test Conditions	Min	Typ.	Max.	Units
$I_S$	Continuous Source Current	$V_G = V_D = 0\text{ V}$ , Force Current	--	--	100	A
$I_{SM}$	Pulsed Source Current		--	--	200	A
$V_{SD}$	Diode Forward Voltage	$V_{GS} = 0\text{ V}$ , $I_S = 1\text{ A}$ , $T_J = 25^\circ\text{C}$	--	--	1	V

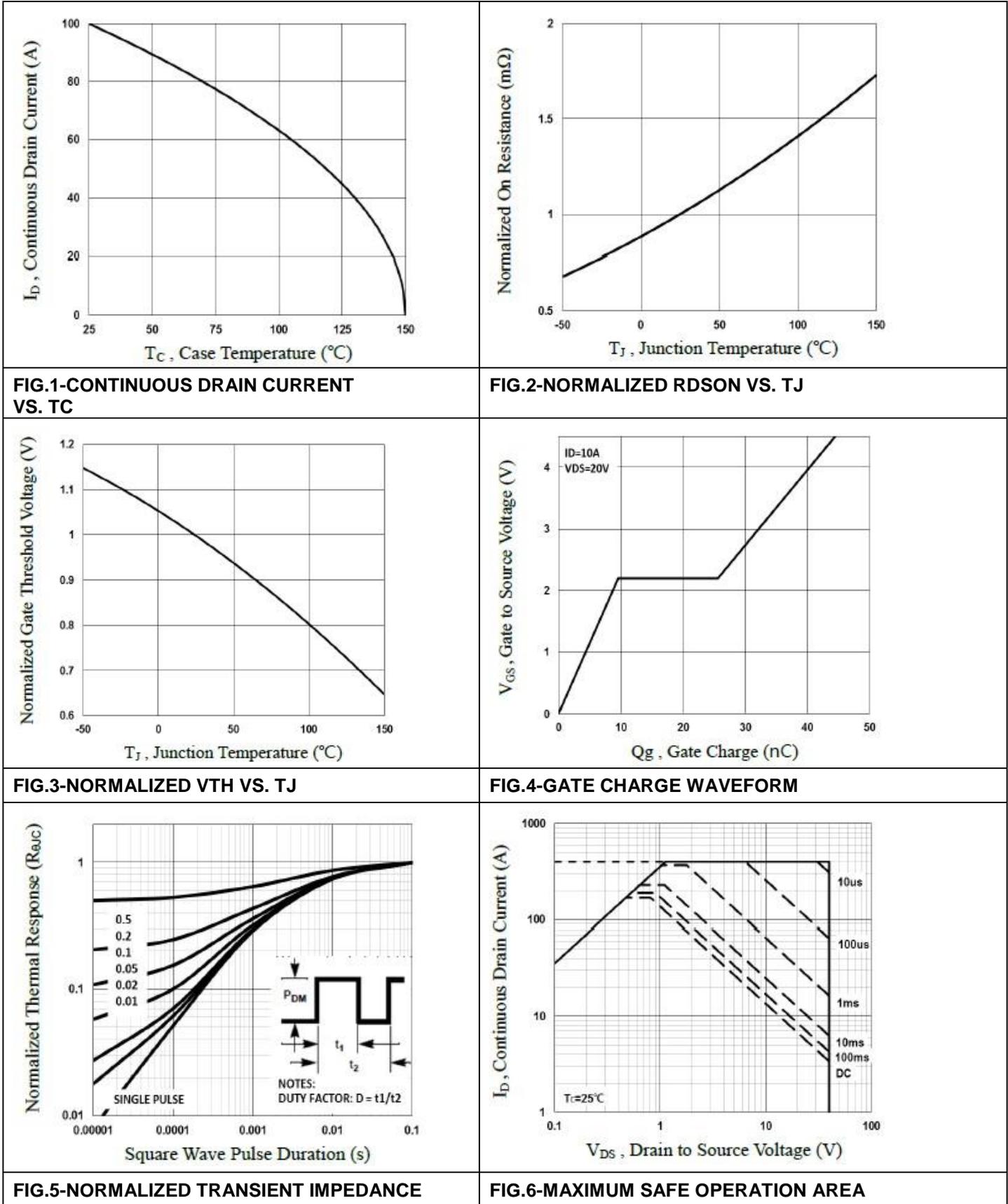
**Note :**

- 1.Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=25\text{V}$ ,  $V_{GS}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=79\text{A}$ ., Starting  $T_J=25^\circ\text{C}$
- 3.The data tested by pulsed , pulse width  $\cong 300\mu\text{s}$  , duty cycle  $\cong 2\%$ .
- 4.Essentially independent of operating temperature.

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### 40V N-Channel MOSFETs

#### ■ Characteristics Curve



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40V N-Channel MOSFETs

■ Characteristics Curve

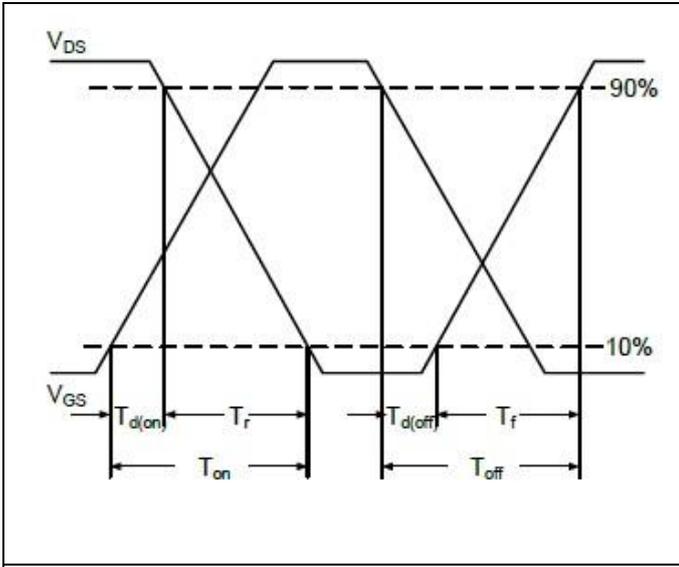


FIG.7-SWITCHING TIME WAVEFORM

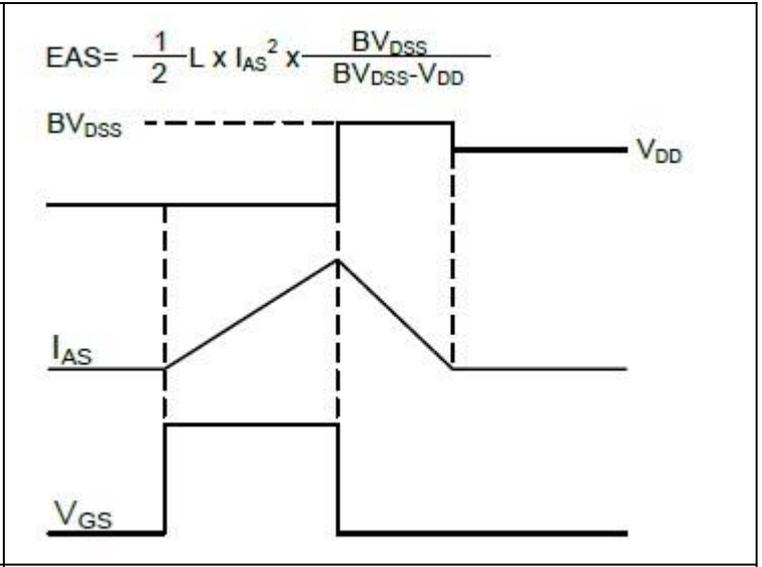


FIG.8-EAS WAVEFORM

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